ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES International and P	IPC, Bannock	burn, Illinois. A	ll rights reserved u ntions.	nder both	This docume level parts, th	ent is a declar he declaration	ration on n enco	of the substance ompasses all lo	es withir wer level	the manufact materials for	turer listed i which the n	tem. No nanufac	ote: if the	e item is an as s engineering	sembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier Information															
Company name* Company uniq			ique ID	Unique I			nique ID Authority				Respons	Response Date*			
nsemi											2024-04	-24			
ontact Name	Title - Conta	Title - Contact				Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com					
Authorized Representative* Title			tle - Representative			Phone - Representative*				Email -	Email - Representative*				
roduct-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com					
Requester Item Number	uester Item Number Mfr Item Nu			Effective Date Version Manufacturing Site Weight*				UOM	Unit Type						
	NOIX2	X2SN016KB-LTI XGS16MP, 12port		rt, Mono,CRA_	_0D	2024-04-24 TA1			:	2074.87	7	mg	Each		
Ianufacturing Proccess Inform	ation		1			1					I			1	1
Terminal Plating / Grid Array M	g / Grid Array Material Terminal Base Alloy		Alloy J	STD-020 MSL Rating		Peak Process Body Temperatur		ture Ma	are Max Time at Peak Temper		ure N	Number of	of Reflow Cyc	les	
Precious metal (e.g. Ag,Au, NiPdAu) (no CU Sn)		CU Alloy	4	4		245 C		С	30	<b>30</b> sec		ds 3			
omments															
or more information regarding materia	al compositior	n please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	S Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl alate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	406.14	mg		Misc.	proprietary data		1.5433	mg
			Supplier	Silicon (Si)	7440-21-3		400.5759	mg
			Supplier	Aluminum (Al)	7429-90-5		4.0208	mg
Die Attach Epoxy	83.58	mg	Supplier	2,2-bis(acryloyloxymethyl)butyl acrylate	15625-89-5		62.685	mg
			Supplier	Imidazole Addition	68490-66-4		2.5074	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		12.537	mg
			Supplier	Silica (SiO2)	14464-46-1		5.8506	mg
maging Lens	865.32	mg	Supplier	Sulfur (S)	7704-34-9		4.3266	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		43.266	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		43.266	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		43.266	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		43.266	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		43.266	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		43.266	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		601.3974	mg
Lid Attach	7.96	mg	Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		0.398	mg
			Supplier	2,3-epoxypropyl-trimethoxysilan	2530-83-8		0.398	mg
			Supplier	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6		5.97	mg
			Supplier	Inorganic filler	7727-43-7, 14807- 96-6		1.194	mg
Mold Compound-Black	377.95	mg		Phenolic Resin	proprietary data		56.6925	mg
			Supplier	Oxirane	39817-09-9		56.6925	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		11.3385	mg
			Supplier	Carbon Black (C)	1333-86-4		3.7795	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		241.888	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		7.559	mg
ubstrate	331.71	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		70.3225	mg
			Supplier	Inorganic filler	Proprietary Data		43.3877	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		4.3454	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.0615	mg
			Supplier	Acetophenone Derivative	Proprietary Data		6.5015	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

			Supplier	Carbon Black (C)	1333-86-4	1.0946	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	1.0946	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	13.003	mg
			Supplier	Copper (Cu)	7440-50-8	157.2969	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	33.6022	mg
Wire Bond - Au	2.21	mg	Supplier	Gold (Au)	7440-57-5	2.21	mg